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## **Abstract of Japanese Patent Office Gazette**

**No. S60-195957**

### **LEAD FRAME**

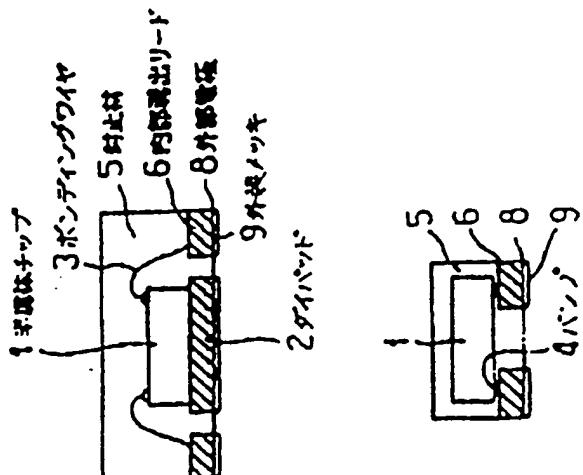
Inventor: Tanigawa Takahiro, et al.  
Applicant: Hitachi Ltd.  
Filed: Mar. 19, 1984  
Disclosed: Oct. 4, 1985

**PURPOSE:** To improve the contacting property between a lead frame and a resin and to enhance the sealability and the reliability by stepwisely forming the side of the lead frame, and increasing the contacting surface with the resin.

**CONSTITUTION:** Projections 8, 15 are formed on tabs 4, 13 of a lead frame, tab hanging lead 5 and the sides of leads 6, 14. The projection 8 is formed by a suitable method. The lead frame 12 is, for example, composed of 42-alloy. A semiconductor chip 9 is formed, for example, of silicon single crystal substrate, many circuit elements are formed in the chip by the know technique, and one circuit function is formed. A resin sealer 11 is formed, for example, of epoxy resin, and molded by a known transfer molding method.

★SONY U11 93-202142/25 ★JP05129473-A  
 Mould package flat-face mounting type semiconductor device  
 exposes bottom surfaces of die pad and inner leads of bottom surface  
 of mould package semiconductor device to be directly connected to  
 circuit pattern of PCB NoAbstract  
 SONY CORP 91.11.06 91JP289882  
 (83.05.25) HOIL 23/28, 23/12, 23/28, 23/50  
 (6pp Dwg.No.1/13)  
 N93-155203

U11-D01A8 U11-D03A9



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